

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in this application.

LISTING OF CLAIMS

1. (Previously Presented) A laminated glazing panel comprising two glass plies, a plastic ply and one or more light emitting diodes which are laminated between the glass plies, wherein the one or more light emitting diodes are mounted on a circuit board, and wherein the glass plies and the plastic ply with the one or more light emitting diodes are laminated at a temperature of about 100°C to 150°C.
2. (Original) A laminated glazing panel as claimed in claim 1 wherein the circuit board includes a flexible circuit board comprising a substrate and a conductive layer.
3. (Original) A laminated glazing panel as claimed in claim 2 wherein the substrate comprises polyimide.
4. (Original) A laminated glazing panel as claimed in claim 2 wherein the substrate comprises polyester.
5. (Previously Presented) A laminated glazing panel as claimed in claim 2 wherein the conductive layer is a metal foil which is adhered to the substrate.

6. (Previously Presented) A laminated glazing panel as claimed in claim 2 wherein the conductive layer is conductive ink which is in direct contact with the substrate.

7. (Previously Presented) A laminated glazing panel as claimed in claim 2 wherein the flexible circuit board further comprises a rigid layer.

8. (Previously Presented) A laminated glazing panel as claimed in claim 2 wherein the flexible circuit board extends outwardly beyond an edge of the glazing panel to enable connection of the circuit board to a power supply.

9. (Previously Presented) A laminated glazing panel as claimed in claim 1 further comprising indicia on at least one ply.

10. (Previously Presented) A laminated glazing panel as claimed in claim 1 wherein the plastic ply comprises a cut-out therein to aid successful lamination of the one or more light emitting diodes mounted on the circuit board in the glazing panel.

11. (Previously Presented) A laminated glazing panel as claimed in claim 1 wherein multiple plastic plies are used to laminate the one or more light emitting diodes mounted on the circuit board in the glazing panel.

12. (Previously Presented) A laminated glazing panel as claimed in claim 11 wherein the one or more light emitting diodes and the circuit board together are at least partially coated in a material compatible with the material of the plastic ply.

13. (Previously Presented) A laminated glazing panel as claimed in claim 1 wherein the plastic ply has a thickness before lamination of 2 mm or less.

14. (Previously Presented) A laminated glazing panel as claimed in claim 1 wherein the thickness of the said panel is 8 mm or less.

15. (Previously Presented) A process for the production of a laminated glazing panel comprising interleaving a plastic ply between two glass plies and laminating the plies, wherein, prior to lamination, a cut-out area is prepared in the plastic ply to receive a circuit board on which one or more light emitting diodes are mounted, said circuit board and one or more light emitting diodes together being at least partially coated with a material compatible with the material of the plastic ply, and the circuit board is positioned in the cut-out area in the plastic ply, wherein the laminating of the two glass plies and the plastic ply with the circuit board on which is mounted the one or more light emitting diodes is performed at a temperature of about 100°C to 150°C.

16. (Previously Presented) A process for the production of a laminated glazing panel comprising pairing together two plastic plies, preparing a cut-out area in the upper plastic ply to receive a circuit board on which one or more light emitting

diodes are mounted, positioning said circuit board in the cut-out area, joining a further plastic ply to the paired plastic plies, thereby creating a composite ply, interleaving the composite ply between two glass plies, and laminating the two glass plies and the composite ply, including the circuit board on which is mounted the one or more light emitting diodes, at a temperature of about 100°C to 150°C.

17. (Original) A process for the production of a laminated glazing panel according to claim 16 wherein the circuit board and one or more light emitting diodes together are at least partially coated with a material compatible with the material of the plastic ply.

18. (Previously Presented) A process for the production of a laminated glazing panel according to claim 15 wherein the overall thickness of the coated circuit board on which one or more light emitting diodes are mounted is comparable with the thickness of the plastic ply in which it is positioned.

19. (Canceled)

20. (Previously Presented) A laminated glazing panel as claimed in claim 3 wherein the conductive layer is a metal foil which is adhered to the substrate.

21. (Previously Presented) A laminated glazing panel as claimed in claim 1 wherein the plastic ply is made of polyvinylbutyral (PVB).

22. (Previously Presented) A process for the production of a laminated glazing panel according to claim 15 wherein the plastic ply is made of polyvinylbutyral (PVB).

23. (Previously Presented) A process for the production of a laminated glazing panel according to claim 16 wherein the two plastic plies that are paired together are made of polyvinylbutyral (PVB).

24. (Previously Presented) A laminated glazing panel as claimed in claim 1 wherein the glass plies and the plastic ply with the one or more light emitting diodes are laminated at a pressure of about 5 to 15 atmospheres.

25. (Previously Presented) A process for the production of a laminated glazing panel according to claim 15 wherein, the laminating of the two glass plies and the plastic ply with the circuit board on which is mounted the one or more light emitting diodes is performed at a pressure of about 5 to 15 atmospheres.

26. (Previously Presented) A process for the production of a laminated glazing panel according to claim 16 wherein the two glass plies and the composite ply including the circuit board on which the one or more light emitting diodes are mounted are laminated at a pressure of about 5 to 15 atmospheres.

27. (Previously Presented) A laminated glazing panel as claimed in claim 2 wherein the laminated glazing panel possesses a thickness equal to or less than 8 mm.

28. (Previously Presented) A process for the production of a laminated glazing panel according to claim 15 wherein the laminated glazing panel possesses a thickness equal to or less than 8 mm.

29. (Previously Presented) A process for the production of a laminated glazing panel according to claim 16 wherein the laminated glazing panel possesses a thickness equal to or less than 8 mm.

30. (Previously Presented) A laminated glazing panel comprising two glass plies, a plastic ply and a light emitting diode device laminated between the glass plies, the light emitting diode device which is laminated between the glass plies comprising one or more light emitting diodes mounted on a circuit board, wherein the glass plies and the plastic ply with the one or more light emitting diodes are laminated at a temperature of about 100°C to 150°C, wherein the laminated glazing panel possesses a thickness of 8 mm or less, and the light emitting diode device possesses a thickness less than 0.8 mm.

31. (Previously Presented) A laminated glazing panel as claimed in claim 30 wherein the thickness of the light emitting diode device is less than the thickness of the plastic ply.

32. (Previously Presented) A laminated glazing panel as claimed in claim 30 wherein the glass plies, the plastic ply and the light emitting diode device are laminated at a pressure of about 5 to 15 atmospheres.